

Title (en)

Preparing substrates containing polymers for metallization

Title (de)

Herstellung von Substraten mit Polymeren zur Metallisierung

Title (fr)

Préparation de substrats contenant des polymères pour la métallisation

Publication

**EP 2287357 B1 20160413 (EN)**

Application

**EP 10173029 A 20100817**

Priority

US 27450509 P 20090818

Abstract (en)

[origin: EP2287357A2] Methods of swelling and topographically altering polymers of substrates using low foaming compositions are disclosed. Solvent swells which are stable, homogeneous and low foaming are applied to substrates containing polymers to swell and soften the polymers followed by applying an oxidizer to topographically alter and desmear the polymers in preparation for metallization of the substrate.

IPC 8 full level

**C08J 7/02** (2006.01); **C23C 18/04** (2006.01); **C23C 18/16** (2006.01); **C23C 18/20** (2006.01); **C23C 18/30** (2006.01); **C23C 18/24** (2006.01); **C23C 18/28** (2006.01); **C23C 18/40** (2006.01)

CPC (source: EP KR US)

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**EP 2287357 A2 20110223**; **EP 2287357 A3 20140924**; **EP 2287357 B1 20160413**; CN 101994105 A 20110330; CN 105220132 A 20160106; CN 105220132 B 20180420; JP 2011099087 A 20110519; JP 5676970 B2 20150225; KR 20110018849 A 20110224; TW 201113393 A 20110416; TW I465603 B 20141221; US 2011064870 A1 20110317

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